

**In The Title:**

Please amend the title to read --METHOD FOR DISTRIBUTING CONNECTION PADS  
ON A SEMICONDUCTOR DIE--.

**In The Specification:**

On page between the title and "BACKGROUND OF THE INVENTION" insert:

**CROSS-REFERENCE TO RELATED APPLICATION**

This is a divisional of copending application Serial No. 08/747,325, filed November 12,  
1996.

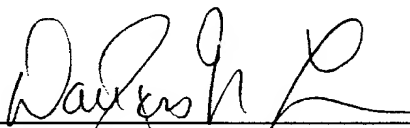
**In The Claims**

Please cancel without prejudice or disclaimer claims 1-21.

**Remarks**

It is requested that the Examiner take the foregoing into account when considering this  
divisional application.

Respectfully submitted,

  
\_\_\_\_\_  
Douglas N. Larson  
Registration No. 29,401

Dated: August 14, 1997

**OPPENHEIMER POMS SMITH**  
2029 Century Park East, Suite 3800  
Los Angeles, California 90067  
Telephone: (310) 788-5000  
Facsimile: (310) 277-1297